

each of said mask patterns respectively prepared for said plural circuit elements has a mark for positioning, and positioning of said mask patterns is performed by superposing one of said marks on another of said marks.

23. A semiconductor device manufactured by the method according to Claim 21.

24. A semiconductor device manufactured by the method according to Claim 22.--

#### REMARKS

Favorable consideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 1-20 canceled, and Claims 21-24 added by way of the present preliminary amendment. Claims 21-24 correspond to non-elected claims 51-54 of the parent application and therefore addition of these claims is not believed to raise a question of new matter.

Accordingly, examination in the merits is believed to be in order and an early and favorable action is respectfully requested.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.

*Edwin D. Garlepp*

Gregory J. Maier  
Registration No. 25,599  
Attorney of Record  
Edwin D. Garlepp  
Registration No. 45,330



**22850**

Tel. No. (703) 413-3000

Fax #: (703) 413-2220

GJM:EDG:fbl

I:\atty\edg\0057\202009\prel. am.wpd